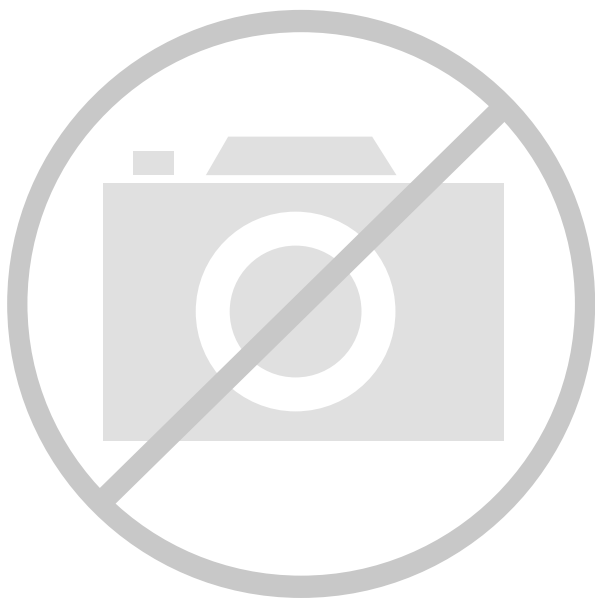




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	792
Total RAM Bits	-
Number of I/O	101
Number of Gates	30000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	128-TQFP
Supplier Device Package	128-VTQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/aglp030v5-vqg128

I/Os Per Package ¹

IGLOO PLUS Devices	AGLP030	AGLP060	AGLP125
Package	Single-Ended I/Os		
CS201	120	157	–
CS281	–	–	212
CS289	120	157	212
VQ128	101	–	–
VQ176	–	137	–

Note: When the Flash*Freeze pin is used to directly enable Flash*Freeze mode and not used as a regular I/O, the number of single-ended user I/Os available is reduced by one.

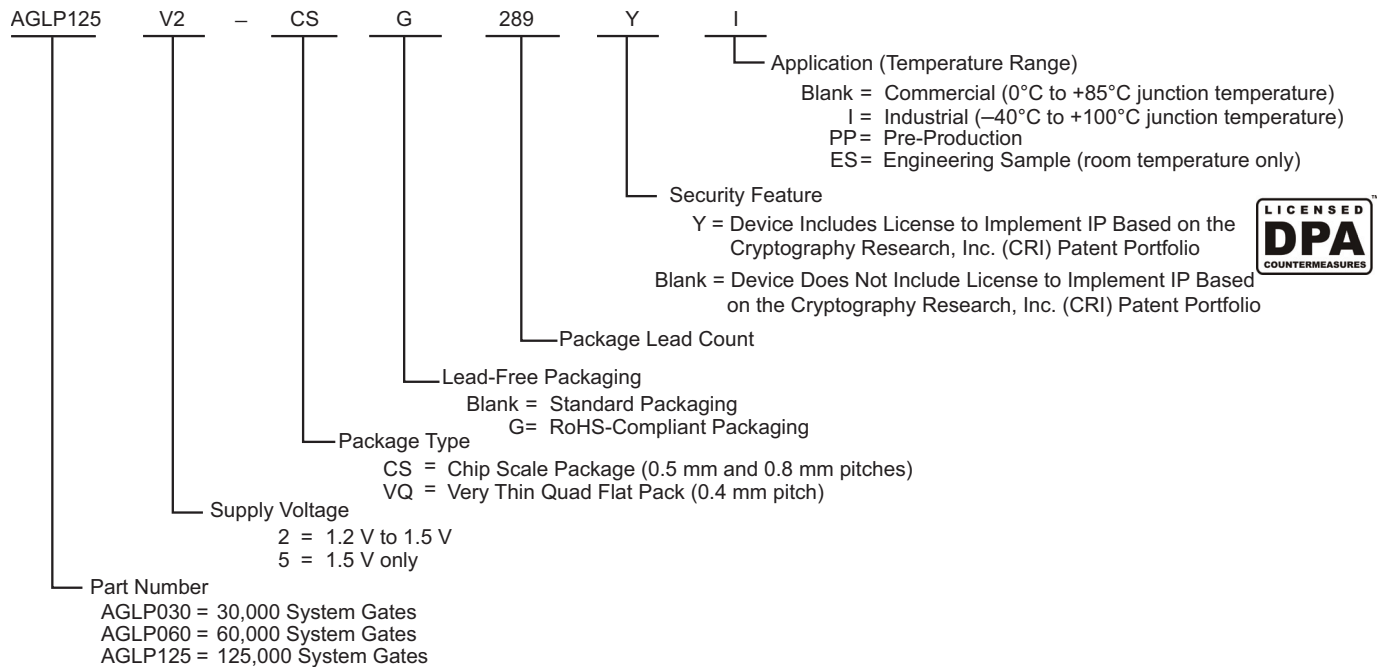
Table 2 • IGLOO PLUS FPGAs Package Size Dimensions

Package	CS201	CS281	CS289	VQ128	VQ176
Length × Width (mm/mm)	8 × 8	10 × 10	14 × 14	14 × 14	20 × 20
Nominal Area (mm ²)	64	100	196	196	400
Pitch (mm)	0.5	0.5	0.8	0.4	0.4
Height (mm)	0.89	1.05	1.20	1.0	1.0

IGLOO PLUS Device Status

IGLOO PLUS Device	Status
AGLP030	Production
AGLP060	Production
AGLP125	Production

IGLOO PLUS Ordering Information



1. Marking information: IGLOO PLUS V2 devices do not have a V2 marking, but IGLOO PLUS V5 devices are marked accordingly.
2. "G" indicates RoHS-compliant packages.

Overview of I/O Performance

Summary of I/O DC Input and Output Levels – Default I/O Software Settings

Table 2-21 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings

I/O Standard	Drive Strength	Equiv. Software Default Drive Strength Option ²	Slew Rate	VIL		VIH		VOL	VOH	IOL ¹	IOH ¹
				Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA
3.3 V LVTTTL / 3.3 V LVCMOS	12 mA	12 mA	High	–0.3	0.8	2	3.6	0.4	2.4	12	12
3.3 V LVCMOS Wide Range ³	100 μ A	12 mA	High	–0.3	0.8	2	3.6	0.2	VDD 3 0.2	0.1	0.1
2.5 V LVCMOS	12 mA	12 mA	High	–0.3	0.7	1.7	3.6	0.7	1.7	12	12
1.8 V LVCMOS	8 mA	8 mA	High	–0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.45	VCCI – 0.45	8	8
1.5 V LVCMOS	4 mA	4 mA	High	–0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	4	4
1.2 V LVCMOS ⁴	2 mA	2 mA	High	–0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	2	2
1.2 V LVCMOS Wide Range ^{4,5}	100 μ A	2 mA	High	–0.3	0.3 * VCCI	0.7 * VCCI	3.6	0.1	VCCI – 0.1	0.1	0.1

Notes:

1. Currents are measured at 85°C junction temperature.
2. Note that 1.2 V LVCMOS and 3.3 V LVCMOS wide range are applicable to 100 μ A drive strength only. The configuration will not operate at the equivalent software default drive strength. These values are for normal ranges only.
3. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.
4. Applicable to IGLOO PLUS V2 devices operating at $VCC_I \geq VCC$.
5. All LVCMOS 1.2 V software macros support LVCMOS 1.2 V wide range as specified in the JESD8-12 specification.

Table 2-24 • I/O AC Parameter Definitions

Parameter	Parameter Definition
t_{DP}	Data to Pad delay through the Output Buffer
t_{PY}	Pad to Data delay through the Input Buffer
t_{DOUT}	Data to Output Buffer delay through the I/O interface
t_{EOUT}	Enable to Output Buffer Tristate Control delay through the I/O interface
t_{DIN}	Input Buffer to Data delay through the I/O interface
t_{HZ}	Enable to Pad delay through the Output Buffer—High to Z
t_{ZH}	Enable to Pad delay through the Output Buffer—Z to High
t_{LZ}	Enable to Pad delay through the Output Buffer—Low to Z
t_{ZL}	Enable to Pad delay through the Output Buffer—Z to Low
t_{ZHS}	Enable to Pad delay through the Output Buffer with delayed enable—Z to High
t_{ZLS}	Enable to Pad delay through the Output Buffer with delayed enable—Z to Low

Table 2-29 • I/O Weak Pull-Up/Pull-Down Resistances
Minimum and Maximum Weak Pull-Up/Pull-Down Resistance Values

VCCI	$R_{(WEAK\ PULL-UP)}^1$ (Ω)		$R_{(WEAK\ PULL-DOWN)}^2$ (Ω)	
	Min.	Max.	Min.	Max.
3.3 V	10 K	45 K	10 K	45 K
3.3 V (wide range I/Os)	10 K	45 K	10 K	45 K
2.5 V	11 K	55 K	12 K	74 K
1.8 V	18 K	70 K	17 K	110 K
1.5 V	19 K	90 K	19 K	140 K
1.2 V	25 K	110 K	25 K	150 K
1.2 V (wide range I/Os)	19 K	110 K	19 K	150 K

Notes:

1. $R_{(WEAK\ PULL-UP-MAX)} = (VCCImax - VOHspec) / I_{(WEAK\ PULL-UP-MIN)}$
2. $R_{(WEAK\ PULLDOWN-MAX)} = (VOLspec) / I_{(WEAK\ PULLDOWN-MIN)}$

Table 2-30 • I/O Short Currents IOSH/IOSL

	Drive Strength	IOSL (mA)*	IOSH (mA)*
3.3 V LVTTTL / 3.3 V LVCMOS	2 mA	27	25
	4 mA	27	25
	6 mA	54	51
	8 mA	54	51
	12 mA	109	103
	16 mA	109	103
3.3 V LVCMOS Wide Range	100 μ A	Same as equivalent software default drive	
2.5 V LVCMOS	2 mA	18	16
	4 mA	18	16
	6 mA	37	32
	8 mA	37	32
	12 mA	74	65
1.8 V LVCMOS	2 mA	11	9
	4 mA	22	17
	6 mA	44	35
	8 mA	44	35
1.5 V LVCMOS	2 mA	16	13
	4 mA	33	25
1.2 V LVCMOS	2 mA	26	20
1.2 V LVCMOS Wide Range	100 μ A	26	20

Note: * $T_J = 100^\circ\text{C}$

Timing Characteristics

Applies to 1.5 V DC Core Voltage

Table 2-42 • 3.3 V LVCMOS Wide Range Low Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.7\text{ V}$

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	Units
100 μA	4 mA	STD	0.97	5.85	0.18	1.18	1.64	0.66	5.86	5.05	2.57	2.57	ns
100 μA	6 mA	STD	0.97	4.70	0.18	1.18	1.64	0.66	4.72	4.27	2.92	3.19	ns
100 μA	8 mA	STD	0.97	4.70	0.18	1.18	1.64	0.66	4.72	4.27	2.92	3.19	ns
100 μA	12 mA	STD	0.97	3.96	0.18	1.18	1.64	0.66	3.98	3.70	3.16	3.59	ns
100 μA	16 mA	STD	0.97	3.96	0.18	1.18	1.64	0.66	3.98	3.70	3.16	3.59	ns

Notes:

1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is $\pm 100\text{ }\mu\text{A}$. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

Table 2-43 • 3.3 V LVCMOS Wide Range High Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 2.7\text{ V}$

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	Units
100 μA	4 mA	STD	0.97	3.39	0.18	1.18	1.64	0.66	3.41	2.69	2.57	2.73	ns
100 μA	6 mA	STD	0.97	2.79	0.18	1.18	1.64	0.66	2.80	2.17	2.92	3.36	ns
100 μA	8 mA	STD	0.97	2.79	0.18	1.18	1.64	0.66	2.80	2.17	2.92	3.36	ns
100 μA	12 mA	STD	0.97	2.47	0.18	1.18	1.64	0.66	2.48	1.91	3.16	3.76	ns
100 μA	16 mA	STD	0.97	2.47	0.18	1.18	1.64	0.66	2.48	1.91	3.16	3.76	ns

Notes:

1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is $\pm 100\text{ }\mu\text{A}$. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.
3. Software default selection highlighted in gray.

Timing Characteristics

Applies to 1.2 V DC Core Voltage

Table 2-70 • 1.2 V LVCMOS Wide Range Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.14 V

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	Units
100 μA	2 mA	STD	0.98	8.27	0.19	1.57	2.34	0.67	7.94	6.77	3.00	3.11	ns

Notes:

1. The minimum drive strength for any LVCMOS 1.2 V software configuration when run in wide range is $\pm 100 \mu\text{A}$. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

Table 2-71 • 1.2 V LVCMOS Wide Range High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.14 V

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	Units
100 μA	2 mA	STD	0.98	3.38	0.19	1.57	2.34	0.67	3.26	2.78	2.99	3.24	ns

Notes:

1. The minimum drive strength for any LVCMOS 1.2 V software configuration when run in wide range is $\pm 100 \mu\text{A}$. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
2. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.
3. Software default selection highlighted in gray.

VersaTile Characteristics

VersaTile Specifications as a Combinatorial Module

The IGLOO PLUS library offers all combinations of LUT-3 combinatorial functions. In this section, timing characteristics are presented for a sample of the library. For more details, refer to the [Fusion](#), [IGLOO/e](#), and [ProASIC3/ E Macro Library Guide](#).

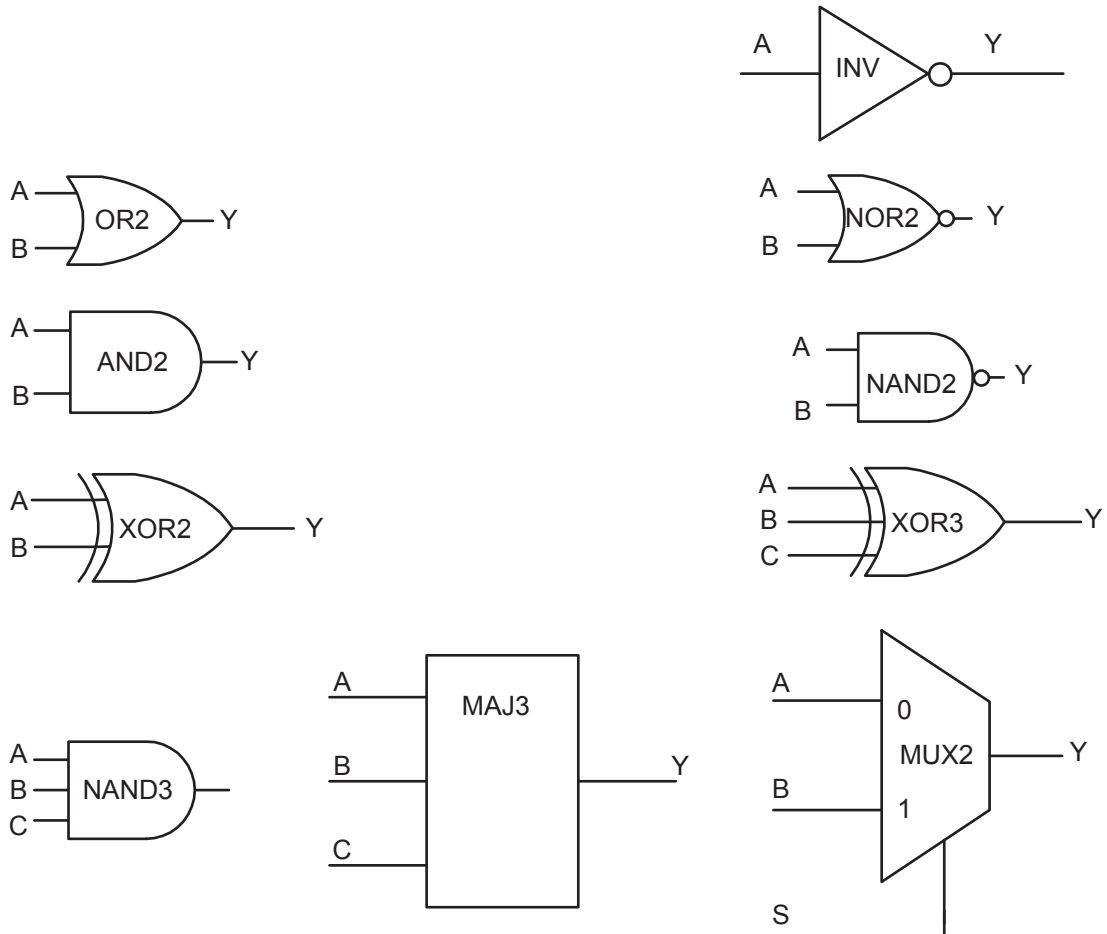
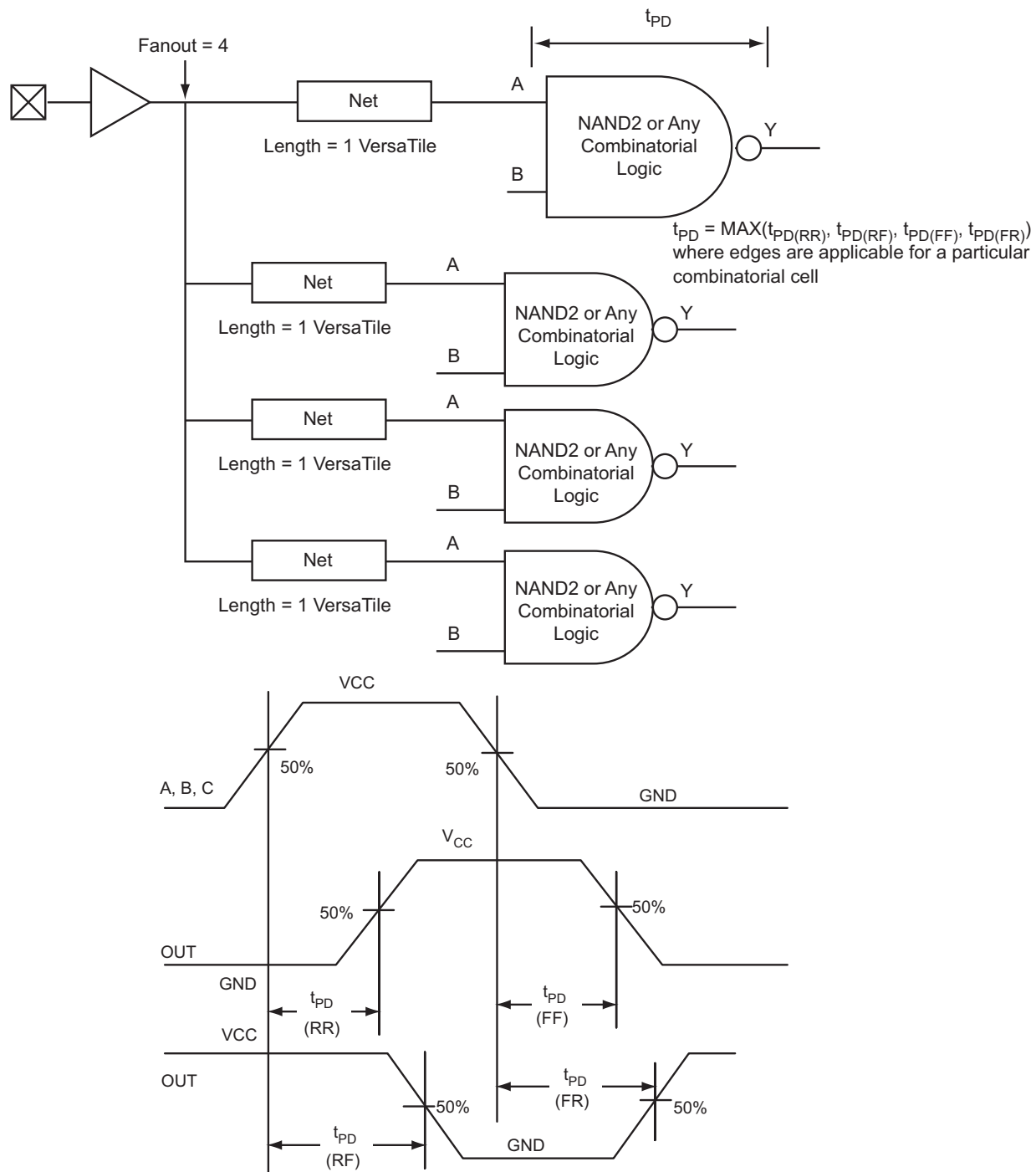


Figure 2-17 • Sample of Combinatorial Cells


Figure 2-18 • Timing Model and Waveforms

Timing Characteristics

1.5 V DC Core Voltage

Table 2-80 • Combinatorial Cell Propagation Delays

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$

Combinatorial Cell	Equation	Parameter	Std.	Units
INV	$Y = !A$	t_{PD}	0.72	ns
AND2	$Y = A \cdot B$	t_{PD}	0.86	ns
NAND2	$Y = !(A \cdot B)$	t_{PD}	1.00	ns
OR2	$Y = A + B$	t_{PD}	1.26	ns
NOR2	$Y = !(A + B)$	t_{PD}	1.16	ns
XOR2	$Y = A \oplus B$	t_{PD}	1.46	ns
MAJ3	$Y = \text{MAJ}(A, B, C)$	t_{PD}	1.47	ns
XOR3	$Y = A \oplus B \oplus C$	t_{PD}	2.12	ns
MUX2	$Y = A !S + B S$	t_{PD}	1.24	ns
AND3	$Y = A \cdot B \cdot C$	t_{PD}	1.40	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

1.2 V DC Core Voltage

Table 2-81 • Combinatorial Cell Propagation Delays

Commercial-Case Conditions: $T_J = 70^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$

Combinatorial Cell	Equation	Parameter	Std.	Units
INV	$Y = !A$	t_{PD}	1.26	ns
AND2	$Y = A \cdot B$	t_{PD}	1.46	ns
NAND2	$Y = !(A \cdot B)$	t_{PD}	1.78	ns
OR2	$Y = A + B$	t_{PD}	2.47	ns
NOR2	$Y = !(A + B)$	t_{PD}	2.17	ns
XOR2	$Y = A \oplus B$	t_{PD}	2.62	ns
MAJ3	$Y = \text{MAJ}(A, B, C)$	t_{PD}	2.66	ns
XOR3	$Y = A \oplus B \oplus C$	t_{PD}	3.77	ns
MUX2	$Y = A !S + B S$	t_{PD}	2.20	ns
AND3	$Y = A \cdot B \cdot C$	t_{PD}	2.49	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-7 on page 2-6](#) for derating values.

Table 2-86 • AGLP125 Global Resource
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	Std.		Units
		Min. ¹	Max. ²	
t_{RCKL}	Input Low Delay for Global Clock	1.36	1.71	ns
t_{RCKH}	Input High Delay for Global Clock	1.39	1.82	ns
$t_{RCKMPWH}$	Minimum Pulse Width High for Global Clock	1.18		ns
$t_{RCKMPWL}$	Minimum Pulse Width Low for Global Clock	1.15		ns
t_{RCKSW}	Maximum Skew for Global Clock		0.43	ns

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

1.2 V DC Core Voltage

Table 2-87 • AGLP030 Global Resource
Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, $V_{CC} = 1.14\text{ V}$

Parameter	Description	Std.		Units
		Min. ¹	Max. ²	
t_{RCKL}	Input Low Delay for Global Clock	1.80	2.09	ns
t_{RCKH}	Input High Delay for Global Clock	1.88	2.27	ns
$t_{RCKMPWH}$	Minimum Pulse Width High for Global Clock	1.40		ns
$t_{RCKMPWL}$	Minimum Pulse Width Low for Global Clock	1.65		ns
t_{RCKSW}	Maximum Skew for Global Clock		0.39	ns

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-7 on page 2-6](#) for derating values.

Embedded SRAM and FIFO Characteristics

SRAM

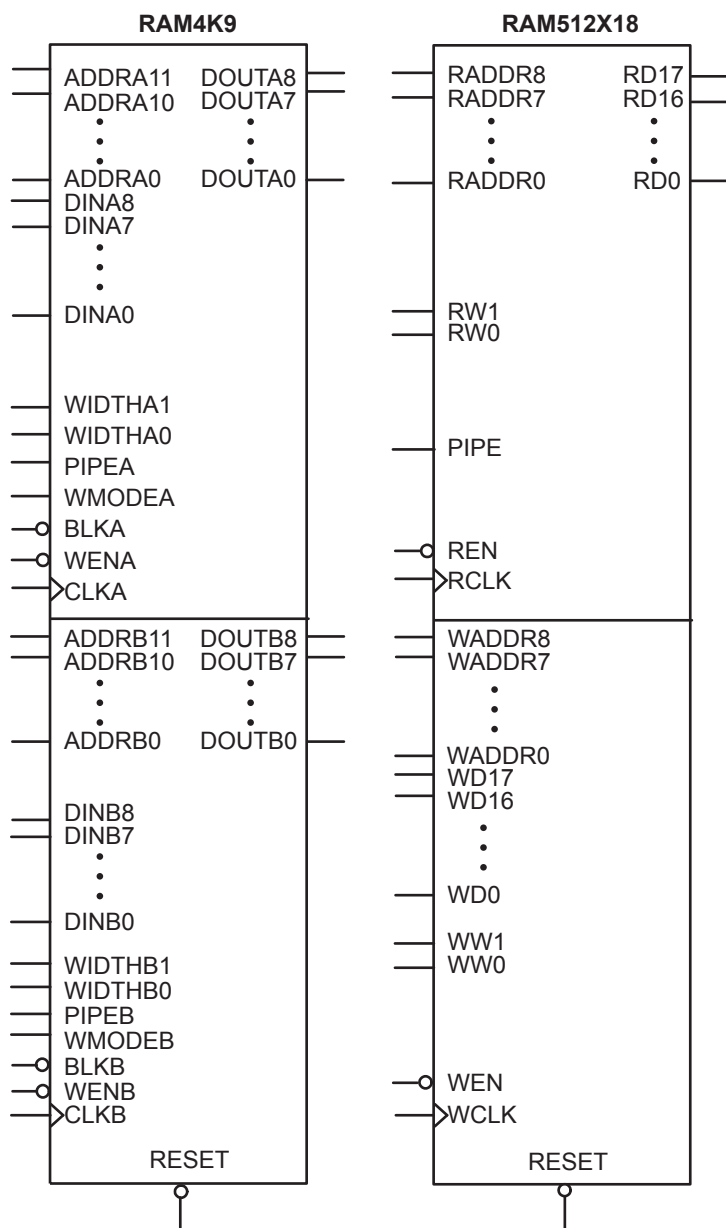


Figure 2-23 • RAM Models

Timing Waveforms

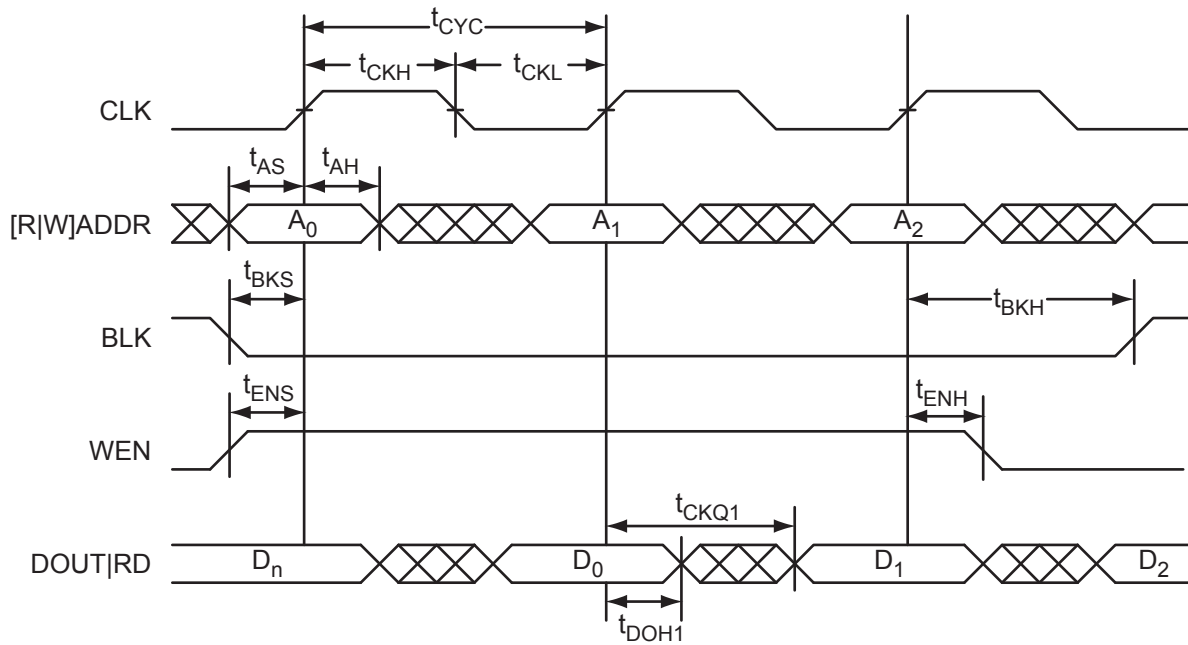


Figure 2-24 • RAM Read for Pass-Through Output. Applicable to Both RAM4K9 and RAM512x18.

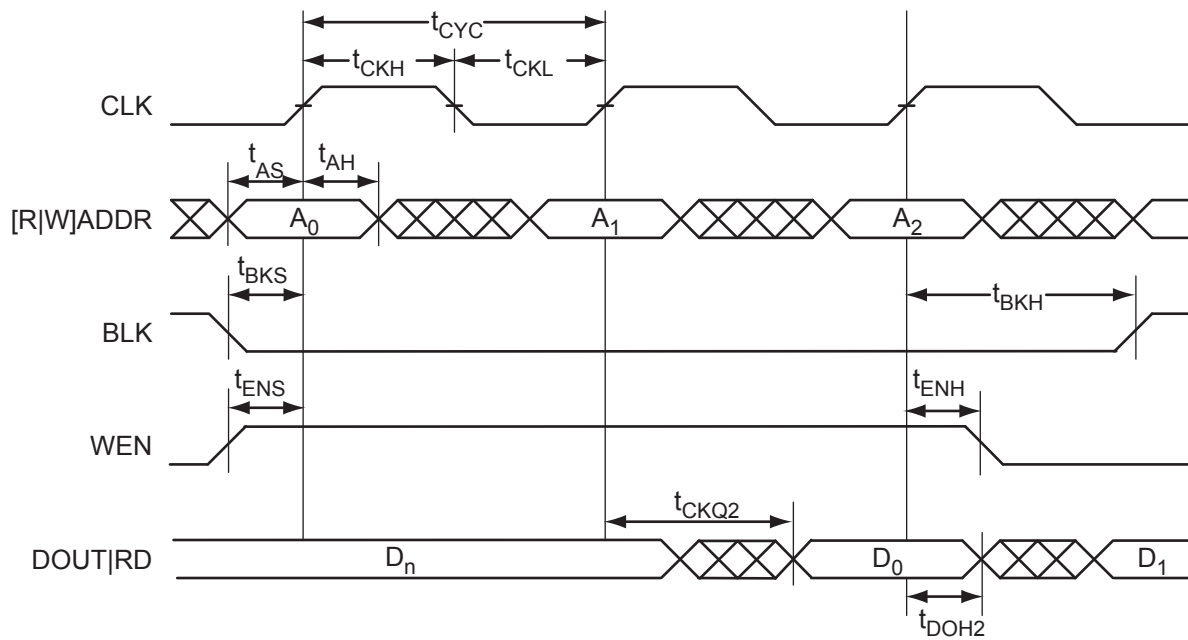


Figure 2-25 • RAM Read for Pipelined Output. Applicable to Both RAM4K9 and RAM512x18.

JTAG Pins

Low power flash devices have a separate bank for the dedicated JTAG pins. The JTAG pins can be run at any voltage from 1.5 V to 3.3 V (nominal). VCC must also be powered for the JTAG state machine to operate, even if the device is in bypass mode; VJTAG alone is insufficient. Both VJTAG and VCC to the part must be supplied to allow JTAG signals to transition the device. Isolating the JTAG power supply in a separate I/O bank gives greater flexibility in supply selection and simplifies power supply and PCB design. If the JTAG interface is neither used nor planned for use, the VJTAG pin together with the TRST pin could be tied to GND.

TCK

Test Clock

Test clock input for JTAG boundary scan, ISP, and UJTAG. The TCK pin does not have an internal pull-up/down resistor. If JTAG is not used, Microsemi recommends tying off TCK to GND through a resistor placed close to the FPGA pin. This prevents JTAG operation in case TMS enters an undesired state.

Note that to operate at all VJTAG voltages, 500 Ω to 1 k Ω will satisfy the requirements. Refer to [Table 3-2](#) for more information.

Table 3-2 • Recommended Tie-Off Values for the TCK and TRST Pins

VJTAG	Tie-Off Resistance
VJTAG at 3.3 V	200 Ω to 1 k Ω
VJTAG at 2.5 V	200 Ω to 1 k Ω
VJTAG at 1.8 V	500 Ω to 1 k Ω
VJTAG at 1.5 V	500 Ω to 1 k Ω

Notes:

1. Equivalent parallel resistance if more than one device is on the JTAG chain
2. The TCK pin can be pulled up/down.
3. The TRST pin is pulled down.

TDI

Test Data Input

Serial input for JTAG boundary scan, ISP, and UJTAG usage. There is an internal weak pull-up resistor on the TDI pin.

TDO

Test Data Output

Serial output for JTAG boundary scan, ISP, and UJTAG usage.

TMS

Test Mode Select

The TMS pin controls the use of the IEEE 1532 boundary scan pins (TCK, TDI, TDO, TRST). There is an internal weak pull-up resistor on the TMS pin.

TRST

Boundary Scan Reset Pin

The TRST pin functions as an active-low input to asynchronously initialize (or reset) the boundary scan circuitry. There is an internal weak pull-up resistor on the TRST pin. If JTAG is not used, an external pull-down resistor could be included to ensure the test access port (TAP) is held in reset mode. The resistor values must be chosen from [Table 3-2](#) and must satisfy the parallel resistance value requirement. The values in [Table 3-2](#) correspond to the resistor recommended when a single device is used, and the equivalent parallel resistor when multiple devices are connected via a JTAG chain.

In critical applications, an upset in the JTAG circuit could allow entrance to an undesired JTAG state. In such cases, Microsemi recommends tying off TRST to GND through a resistor placed close to the FPGA pin.

Note that to operate at all VJTAG voltages, 500 Ω to 1 k Ω will satisfy the requirements.

Special Function Pins

NC

No Connect

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

DC

Do Not Connect

This pin should not be connected to any signals on the PCB. These pins should be left unconnected.

Packaging

Semiconductor technology is constantly shrinking in size while growing in capability and functional integration. To enable next-generation silicon technologies, semiconductor packages have also evolved to provide improved performance and flexibility.

Microsemi consistently delivers packages that provide the necessary mechanical and environmental protection to ensure consistent reliability and performance. Microsemi IC packaging technology efficiently supports high-density FPGAs with large-pin-count Ball Grid Arrays (BGAs), but is also flexible enough to accommodate stringent form factor requirements for Chip Scale Packaging (CSP). In addition, Microsemi offers a variety of packages designed to meet your most demanding application and economic requirements for today's embedded and mobile systems.

Related Documents

IGLOO PLUS Device Family User's Guide

http://www.microsemi.com/soc/documents/IGLOOPLUS_UG.pdf

The following documents provide packaging information and device selection for low power flash devices.

Product Catalog

http://www.microsemi.com/soc/documents/ProdCat_PIB.pdf

Lists devices currently recommended for new designs and the packages available for each member of the family. Use this document or the datasheet tables to determine the best package for your design, and which package drawing to use.

Package Mechanical Drawings

<http://www.microsemi.com/soc/documents/PckgMechDrwns.pdf>

This document contains the package mechanical drawings for all packages currently or previously supplied by Microsemi. Use the bookmarks to navigate to the package mechanical drawings.

Additional packaging materials are available at

<http://www.microsemi.com/soc/products/solutions/package/docs.aspx>.

CS201		CS201		CS201	
Pin Number	AGLP030 Function	Pin Number	AGLP030 Function	Pin Number	AGLP030 Function
H14	IO45RSB1	L15	IO58RSB1	P5	IO87RSB2
H15	IO43RSB1	M1	IO93RSB3	P6	IO86RSB2
J1	GEA0/IO107RSB3	M2	IO92RSB3	P7	IO84RSB2
J2	IO105RSB3	M3	IO97RSB3	P8	IO80RSB2
J3	IO104RSB3	M4	GND	P9	IO74RSB2
J4	IO102RSB3	M5	NC	P10	IO73RSB2
J6	VCCIB3	M6	IO79RSB2	P11	IO76RSB2
J7	GND	M7	IO77RSB2	P12	IO67RSB2
J8	VCC	M8	IO72RSB2	P13	IO64RSB2
J9	GND	M9	IO70RSB2	P14	VPUMP
J10	VCCIB1	M10	IO61RSB2	P15	TRST
J12	NC	M11	IO59RSB2	R1	NC
J13	NC	M12	GND	R2	NC
J14	IO52RSB1	M13	NC	R3	IO91RSB2
J15	IO50RSB1	M14	IO55RSB1	R4	FF/IO90RSB2
K1	IO103RSB3	M15	IO56RSB1	R5	IO89RSB2
K2	IO101RSB3	N1	NC	R6	IO83RSB2
K3	IO99RSB3	N2	NC	R7	IO82RSB2
K4	IO100RSB3	N3	GND	R8	IO85RSB2
K6	GND	N4	NC	R9	IO78RSB2
K7	VCCIB2	N5	IO88RSB2	R10	IO69RSB2
K8	VCCIB2	N6	IO81RSB2	R11	IO62RSB2
K9	VCCIB2	N7	IO75RSB2	R12	IO60RSB2
K10	VCCIB1	N8	IO68RSB2	R13	TMS
K12	NC	N9	IO66RSB2	R14	TDI
K13	IO57RSB1	N10	IO65RSB2	R15	TCK
K14	IO49RSB1	N11	IO71RSB2		
K15	IO53RSB1	N12	IO63RSB2		
L1	IO96RSB3	N13	GND		
L2	IO98RSB3	N14	TDO		
L3	IO95RSB3	N15	VJTAG		
L4	IO94RSB3	P1	NC		
L12	NC	P2	NC		
L13	NC	P3	NC		
L14	IO51RSB1	P4	NC		

CS281	
Pin Number	AGLP125 Function
R15	IO109RSB2
R16	GDA1/IO103RSB1
R18	GDB0/IO102RSB1
R19	GDC0/IO100RSB1
T1	IO171RSB3
T2	GEC0/IO169RSB3
T4	GEB0/IO167RSB3
T5	IO157RSB2
T6	IO158RSB2
T7	IO148RSB2
T8	IO145RSB2
T9	IO143RSB2
T10	GND
T11	IO129RSB2
T12	IO126RSB2
T13	IO125RSB2
T14	IO116RSB2
T15	GDC2/IO107RSB2
T16	TMS
T18	VJTAG
T19	GDB1/IO101RSB1
U1	IO160RSB2
U2	GEA1/IO166RSB3
U6	IO151RSB2
U14	IO121RSB2
U18	TRST
U19	GDA0/IO104RSB1
V1	IO159RSB2
V2	VCCIB3
V3	GEC2/IO162RSB2
V4	IO156RSB2
V5	IO153RSB2
V6	GND
V7	IO144RSB2
V8	IO141RSB2
V9	IO140RSB2

CS281	
Pin Number	AGLP125 Function
V10	IO133RSB2
V11	IO127RSB2
V12	IO123RSB2
V13	IO120RSB2
V14	GND
V15	IO113RSB2
V16	GDA2/IO105RSB2
V17	TDI
V18	VCCIB2
V19	TDO
W1	GND
W2	FF/GEB2/IO163RSB 2
W3	IO155RSB2
W4	IO152RSB2
W5	IO150RSB2
W6	IO147RSB2
W7	IO142RSB2
W8	IO139RSB2
W9	IO136RSB2
W10	VCCIB2
W11	IO128RSB2
W12	IO124RSB2
W13	IO119RSB2
W14	IO115RSB2
W15	IO114RSB2
W16	IO110RSB2
W17	GDB2/IO106RSB2
W18	TCK
W19	GND

CS289		CS289		CS289	
Pin Number	AGLP030 Function	Pin Number	AGLP030 Function	Pin Number	AGLP030 Function
A1	IO03RSB0	C4	NC	E7	IO06RSB0
A2	NC	C5	VCCIB0	E8	IO11RSB0
A3	NC	C6	IO09RSB0	E9	IO22RSB0
A4	GND	C7	IO13RSB0	E10	IO26RSB0
A5	IO10RSB0	C8	IO15RSB0	E11	VCCIB0
A6	IO14RSB0	C9	IO21RSB0	E12	NC
A7	IO16RSB0	C10	GND	E13	IO33RSB0
A8	IO18RSB0	C11	IO29RSB0	E14	IO36RSB1
A9	GND	C12	NC	E15	IO38RSB1
A10	IO23RSB0	C13	NC	E16	VCCIB1
A11	IO27RSB0	C14	NC	E17	NC
A12	NC	C15	GND	F1	IO111RSB3
A13	NC	C16	IO34RSB0	F2	NC
A14	GND	C17	NC	F3	IO116RSB3
A15	NC	D1	NC	F4	VCCIB3
A16	NC	D2	IO119RSB3	F5	IO117RSB3
A17	IO30RSB0	D3	GND	F6	NC
B1	IO01RSB0	D4	IO02RSB0	F7	NC
B2	GND	D5	NC	F8	IO08RSB0
B3	NC	D6	NC	F9	IO12RSB0
B4	NC	D7	NC	F10	NC
B5	IO07RSB0	D8	GND	F11	NC
B6	NC	D9	IO20RSB0	F12	NC
B7	VCCIB0	D10	IO25RSB0	F13	NC
B8	IO17RSB0	D11	NC	F14	GND
B9	IO19RSB0	D12	NC	F15	NC
B10	IO24RSB0	D13	GND	F16	IO37RSB1
B11	IO28RSB0	D14	IO32RSB0	F17	IO41RSB1
B12	VCCIB0	D15	IO35RSB0	G1	IO110RSB3
B13	NC	D16	NC	G2	GND
B14	NC	D17	NC	G3	IO113RSB3
B15	NC	E1	VCCIB3	G4	NC
B16	IO31RSB0	E2	IO114RSB3	G5	NC
B17	GND	E3	IO115RSB3	G6	NC
C1	NC	E4	IO118RSB3	G7	GND
C2	IO00RSB0	E5	IO05RSB0	G8	GND
C3	IO04RSB0	E6	NC	G9	VCC

CS289	
Pin Number	AGLP030 Function
G10	GND
G11	GND
G12	IO40RSB1
G13	NC
G14	IO39RSB1
G15	IO44RSB1
G16	NC
G17	GND
H1	NC
H2	GEC0/IO108RSB3
H3	NC
H4	IO112RSB3
H5	NC
H6	IO109RSB3
H7	GND
H8	GND
H9	GND
H10	GND
H11	GND
H12	NC
H13	NC
H14	IO45RSB1
H15	VCCIB1
H16	GDB0/IO48RSB1
H17	IO42RSB1
J1	NC
J2	GEA0/IO107RSB3
J3	VCCIB3
J4	IO105RSB3
J5	NC
J6	NC
J7	VCC
J8	GND
J9	GND
J10	GND
J11	VCC
J12	IO50RSB1

CS289	
Pin Number	AGLP030 Function
J13	IO43RSB1
J14	IO51RSB1
J15	IO52RSB1
J16	GDC0/IO46RSB1
J17	GDA0/IO47RSB1
K1	GND
K2	GEB0/IO106RSB3
K3	IO102RSB3
K4	IO104RSB3
K5	IO99RSB3
K6	NC
K7	GND
K8	GND
K9	GND
K10	GND
K11	GND
K12	NC
K13	NC
K14	NC
K15	IO53RSB1
K16	GND
K17	IO49RSB1
L1	IO103RSB3
L2	IO101RSB3
L3	NC
L4	GND
L5	NC
L6	NC
L7	GND
L8	GND
L9	VCC
L10	GND
L11	GND
L12	IO58RSB1
L13	IO54RSB1
L14	VCCIB1
L15	NC

CS289	
Pin Number	AGLP030 Function
L16	NC
L17	NC
M1	NC
M2	VCCIB3
M3	IO100RSB3
M4	IO98RSB3
M5	IO93RSB3
M6	IO97RSB3
M7	NC
M8	NC
M9	IO71RSB2
M10	NC
M11	IO63RSB2
M12	NC
M13	IO57RSB1
M14	NC
M15	NC
M16	NC
M17	VCCIB1
N1	NC
N2	NC
N3	IO95RSB3
N4	IO96RSB3
N5	GND
N6	NC
N7	IO85RSB2
N8	IO79RSB2
N9	IO77RSB2
N10	VCCIB2
N11	NC
N12	NC
N13	IO59RSB2
N14	NC
N15	GND
N16	IO56RSB1
N17	IO55RSB1
P1	IO94RSB3

CS289		CS289		CS289	
Pin Number	AGLP060 Function	Pin Number	AGLP060 Function	Pin Number	AGLP060 Function
G13	IO41RSB1	J17	GCA1/IO56RSB1	M4	IO122RSB3
G14	IO47RSB1	K1	GND	M5	GEB0/IO113RSB3
G15	IO49RSB1	K2	GFA0/IO135RSB3	M6	GEB1/IO114RSB3
G16	IO50RSB1	K3	GFB2/IO133RSB3	M7	NC
G17	GND	K4	IO128RSB3	M8	NC
H1	VCOMPLF	K5	IO123RSB3	M9	IO90RSB2
H2	GFB0/IO137RSB3	K6	IO125RSB3	M10	NC
H3	NC	K7	GND	M11	IO83RSB2
H4	IO141RSB3	K8	GND	M12	NC
H5	IO143RSB3	K9	GND	M13	GDA1/IO76RSB1
H6	GFB1/IO138RSB3	K10	GND	M14	GDA0/IO77RSB1
H7	GND	K11	GND	M15	IO71RSB1
H8	GND	K12	IO64RSB1	M16	IO69RSB1
H9	GND	K13	IO61RSB1	M17	VCCIB1
H10	GND	K14	IO66RSB1	N1	IO119RSB3
H11	GND	K15	IO65RSB1	N2	IO120RSB3
H12	GCC1/IO52RSB1	K16	GND	N3	GEC0/IO115RSB3
H13	IO51RSB1	K17	GCC2/IO60RSB1	N4	GEA0/IO111RSB3
H14	GCA0/IO57RSB1	L1	GFA2/IO134RSB3	N5	GND
H15	VCCIB1	L2	GFC2/IO132RSB3	N6	NC
H16	GCA2/IO58RSB1	L3	IO127RSB3	N7	IO104RSB2
H17	GCC0/IO53RSB1	L4	GND	N8	IO98RSB2
J1	VCCPLF	L5	IO121RSB3	N9	IO96RSB2
J2	GFA1/IO136RSB3	L6	GEC1/IO116RSB3	N10	VCCIB2
J3	VCCIB3	L7	GND	N11	NC
J4	IO131RSB3	L8	GND	N12	NC
J5	IO130RSB3	L9	VCC	N13	GDB2/IO79RSB2
J6	IO129RSB3	L10	GND	N14	NC
J7	VCC	L11	GND	N15	GND
J8	GND	L12	GDC1/IO72RSB1	N16	GDB0/IO75RSB1
J9	GND	L13	GDB1/IO74RSB1	N17	GDC0/IO73RSB1
J10	GND	L14	VCCIB1	P1	IO118RSB3
J11	VCC	L15	IO70RSB1	P2	IO117RSB3
J12	GCB2/IO59RSB1	L16	IO68RSB1	P3	GND
J13	GCB1/IO54RSB1	L17	IO67RSB1	P4	NC
J14	IO62RSB1	M1	IO126RSB3	P5	NC
J15	IO63RSB1	M2	VCCIB3	P6	IO106RSB2
J16	GCB0/IO55RSB1	M3	IO124RSB3	P7	IO99RSB2